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CLAIM AMENDMENTS

IN THE CLAIMS

This listing of the claims will replace all prior versions, and listing, of claims in the application or previous response to office action:

1. (Currently Amended) A method for fabricating an intensity balanced photomask, the method comprising:

forming an alternating aperture phase shifting photomask pattern on a substrate having trenches formed therein; and

forming a layer of antireflective material within the bottom of at least one trench, the antireflective material substantially transparent to at least one wavelength.

- 2. (Currently Amended) The method of Claim 1 wherein the antireflective material further comprises Magnesium Fluoride (MgF2) (MgF2).
- 3. (Original) The method of Claim 1 further comprising forming a layer of antireflective material within the bottom of a plurality of the trenches.
- 4. (Original) The method of Claim 1 further comprising forming the layer of antireflective material using a vacuum evaporation technique.
- 5. (Original) The method of Claim 1 further comprising selecting the depth of the antireflective layer to increase light coupling into the trench.
- 6. (Original) The method of Claim 1 further comprising:
 selecting a light source having a wavelength for use with the photomask; and
 selecting an AR layer thickness of approximately the wavelength divided by four
 times the refractive index of the antireflective material.

- 7. (Original) The method of Claim 6 further comprising selecting an AR layer thickness equal to the wavelength divided by four times the refractive index of the antireflective material.
- 8. (Original) The method of Claim 1 further comprising the substrate formed from quartz.
- 9. (Currently Amended) The method of Claim 1 further comprising depositing an absorber layer on the alternating aperture phase shifting photomask <u>pattern</u>.
- 10. (Original) The method of Claim 1 further comprising depositing a protective layer over the photomask to prevent electrostatic discharge.
- 11. (Currently Amended) A method for fabricating a phase shifting mask, the method comprising:

providing an etched transparent substrate having a recessed transmissive area, the substrate having a first refractive index;

depositing a <u>transparent</u> antireflective layer in the recessed transmissive area, the antireflective layer having a second refractive index less than the first refractive index;

depositing an absorber layer on the etched substrate; and patterning the absorber layer.

- 12. (Original) The method of Claim 11, wherein the antireflective layer has a thickness of approximately one-quarter of a wavelength of incident light.
- 13. (Currently Amended) The method of Claim 11, wherein the antireflective material layer comprises Magnesium Fluoride (MgF2) (MgF2).
- 14. (Currently Amended) An alternating aperture phase shifting photomask, comprising:

an etched transparent substrate including a recessed transmissive portion;

an antireflective layer deposited on a bottom surface of the recessed transmissive portion, the antireflective layer substantially transparent to at least one wavelength; and a patterned absorber layer deposited on the substrate.

- 15. (Currently Amended) The photomask phase shifting mask of Claim 14 further comprising the antireflective layer having a thickness of approximately one-quarter wavelength of incident light.
- 16. (Currently Amended) The photomask phase shifting mask of Claim 14 further comprising the antireflective layer having a thickness of approximately the wavelength of incident light divided by four times the refractive index of the antireflective material layer.
- 17. (Original) The phase shifting mask of Claim 14, wherein the substrate has a first refractive index and the antireflective layer has a second refractive index less than the first refractive index.
- 18. (Currently Amended) The phase shifting mask of Claim 14, wherein the antireflective material layer comprises Magnesium Fluoride (MgF2) (MgF2).
- 19. (Currently Amended) The phase shifting mask of Claim 14 further comprising the antireflective material layer deposited using a directional technique.
- 20. (Currently Amended) The phase shifting mask of Claim 14 further comprising the antireflective material <u>layer</u> deposited using a vacuum evaporation technique.